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(12) **United States Design Patent**
Xiao

(10) **Patent No.:** **US D933,042 S**

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(54) **WIRELESS HEADSET MICROPHONE**

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(**) Term: **15 Years**

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(51) **LOC (13) Cl.** **14-01**

(52) **U.S. Cl.**

USPC **D14/206**

(58) **Field of Classification Search**

USPC D14/206, 225, 226, 223, 205, 240, 249,
D14/218; 181/135; 381/380, 381, 374,
381/375; 455/90.3, 575.1, 569.1;
379/430

CPC H04R 1/10; H04R 1/1066; H04R 1/1016;
H04R 25/00; H04R 25/02; H04R 19/04;
H04M 1/00; A61F 11/08; G09G 5/00

See application file for complete search history.

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Primary Examiner — Paula Allen Greene

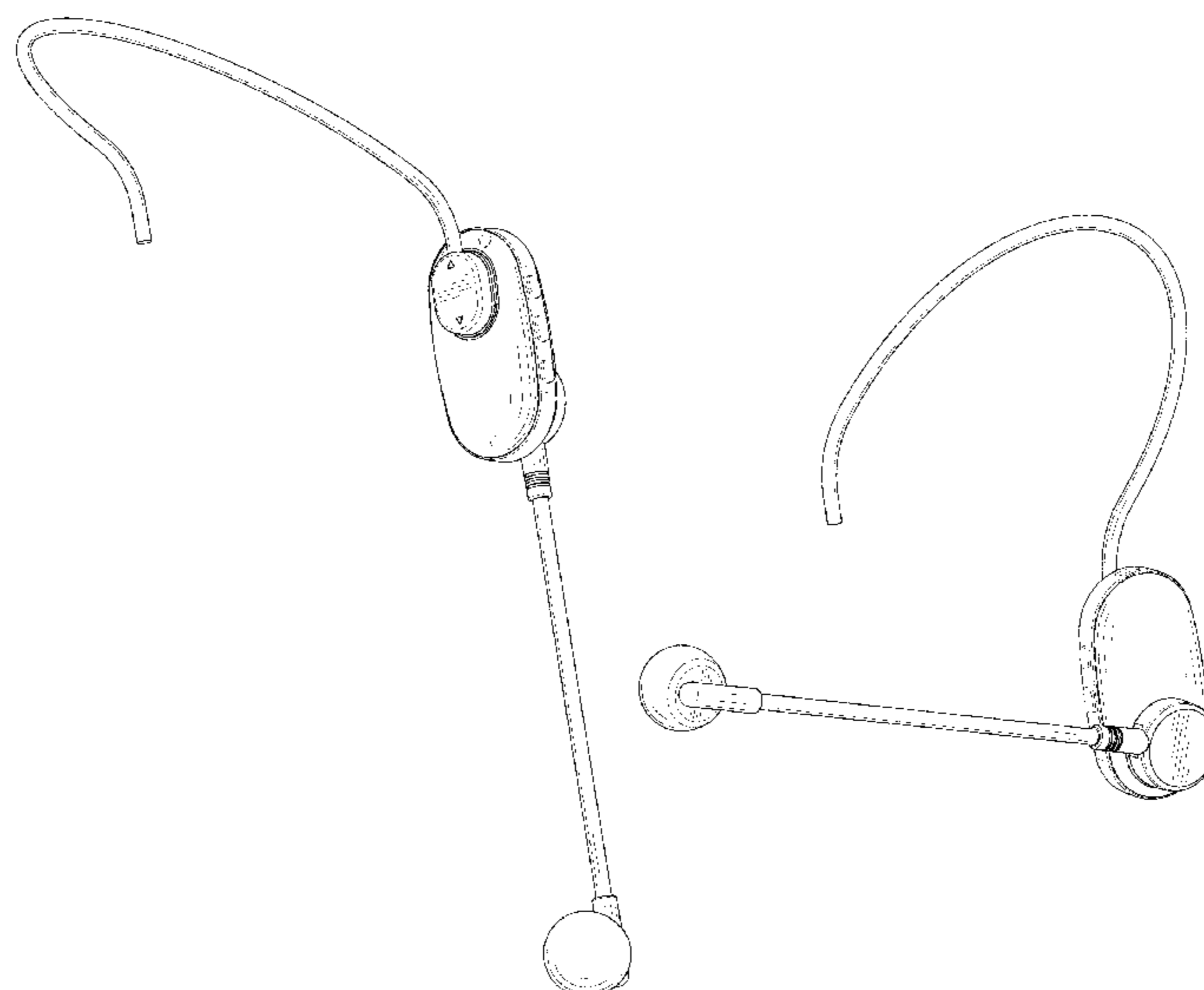
(57) **CLAIM**

The ornamental design for a wireless headset microphone, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a wireless headset microphone showing my new design;
 FIG. 2 is a front view thereof;
 FIG. 3 is a back view thereof;
 FIG. 4 is a left side view thereof;
 FIG. 5 is a right side view thereof;
 FIG. 6 is a top view thereof;
 FIG. 7 is a bottom view thereof;
 FIG. 8 is another perspective view thereof; and,
 FIG. 9 is disassembled perspective view thereof.
 The broken lines shown in the drawings depict portions of the wireless headset microphone in which the design is embodied that form no part of the claimed design.

1 Claim, 9 Drawing Sheets



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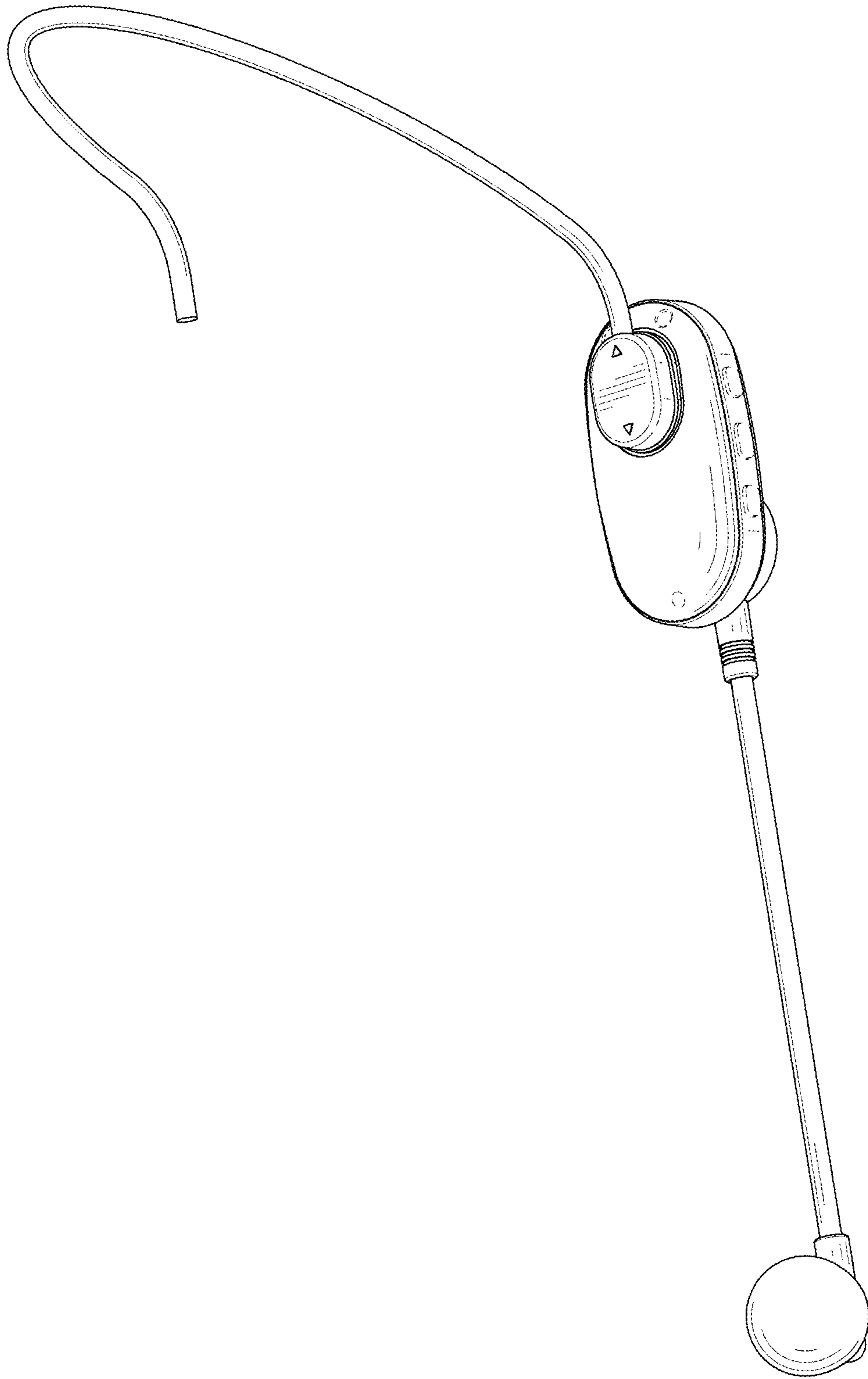


FIG. 1

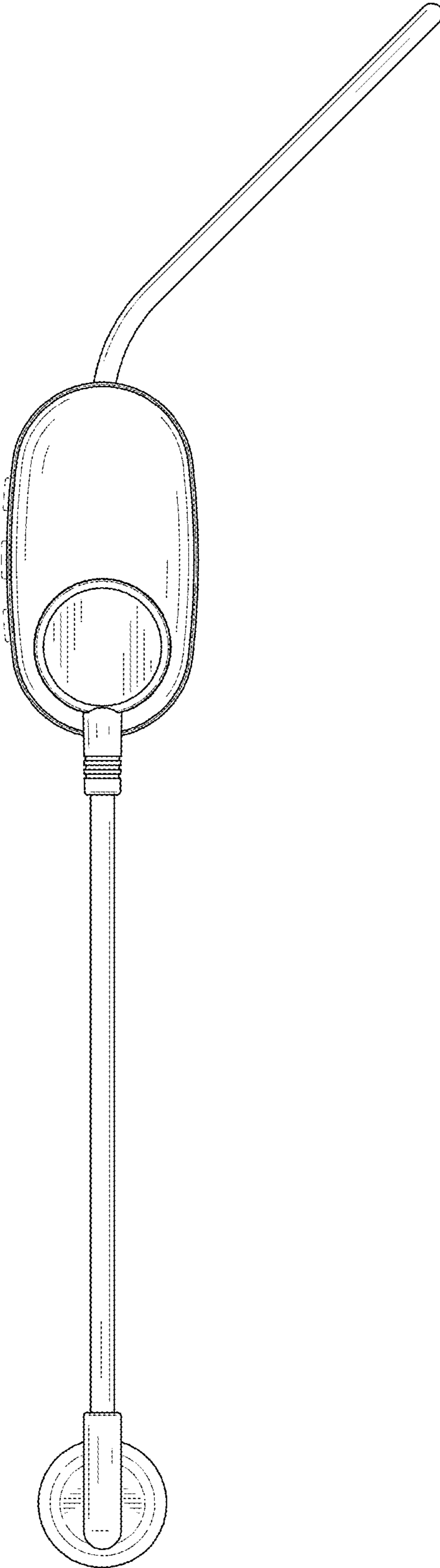


FIG. 2

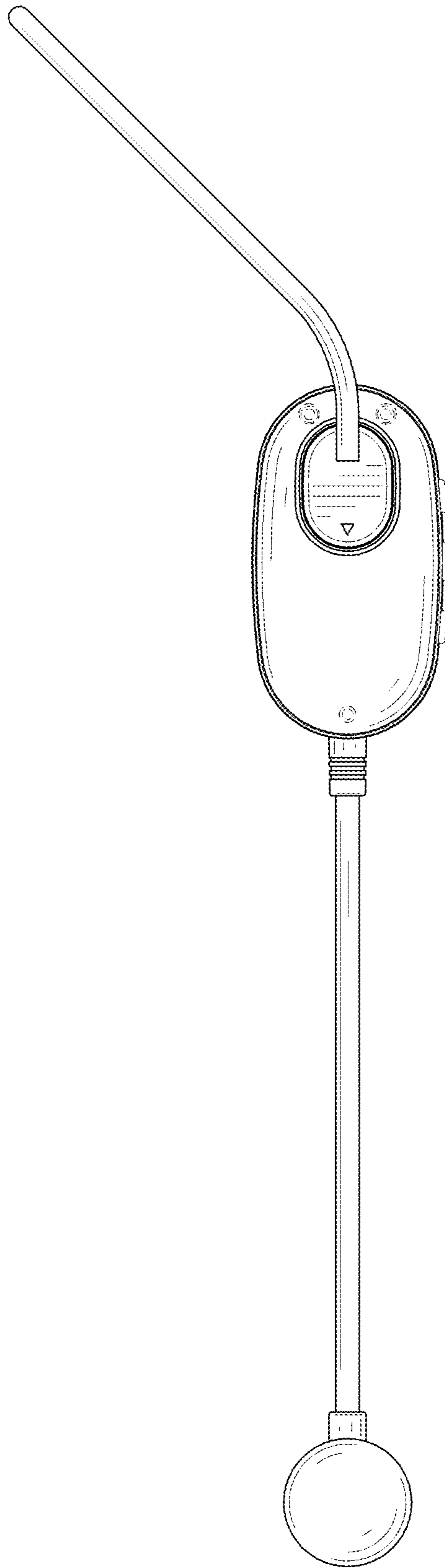


FIG. 3

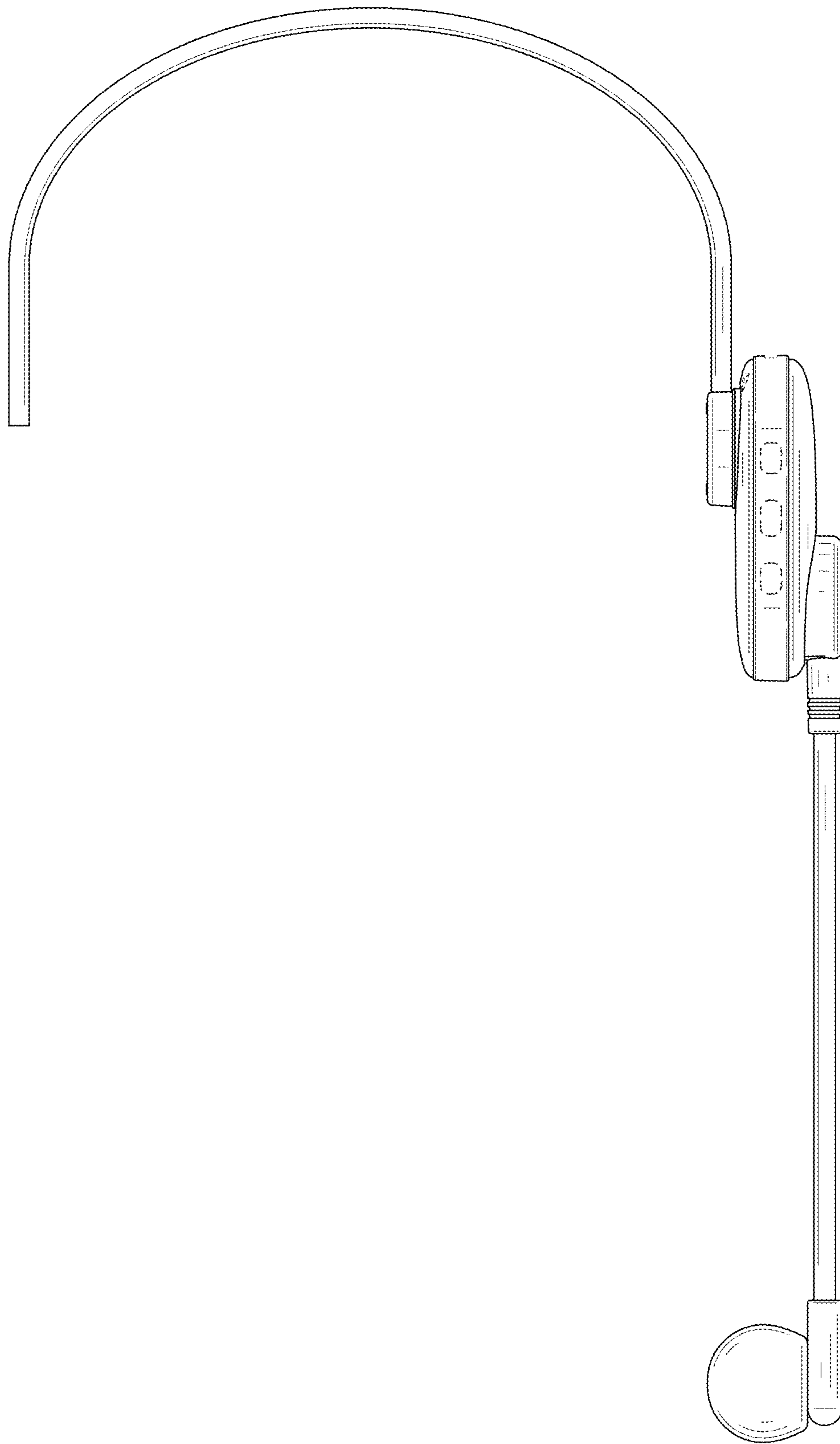


FIG. 4

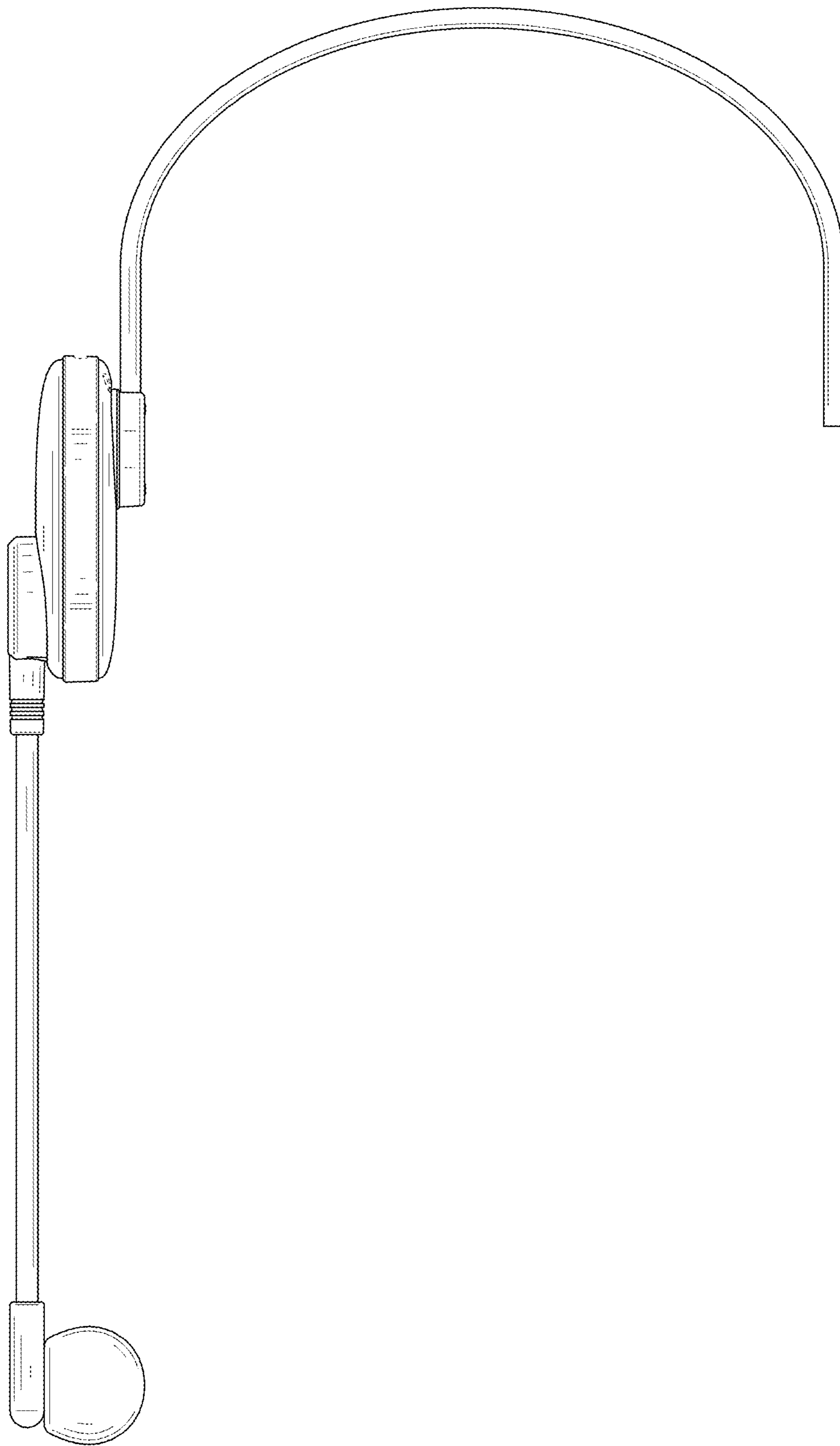


FIG. 5

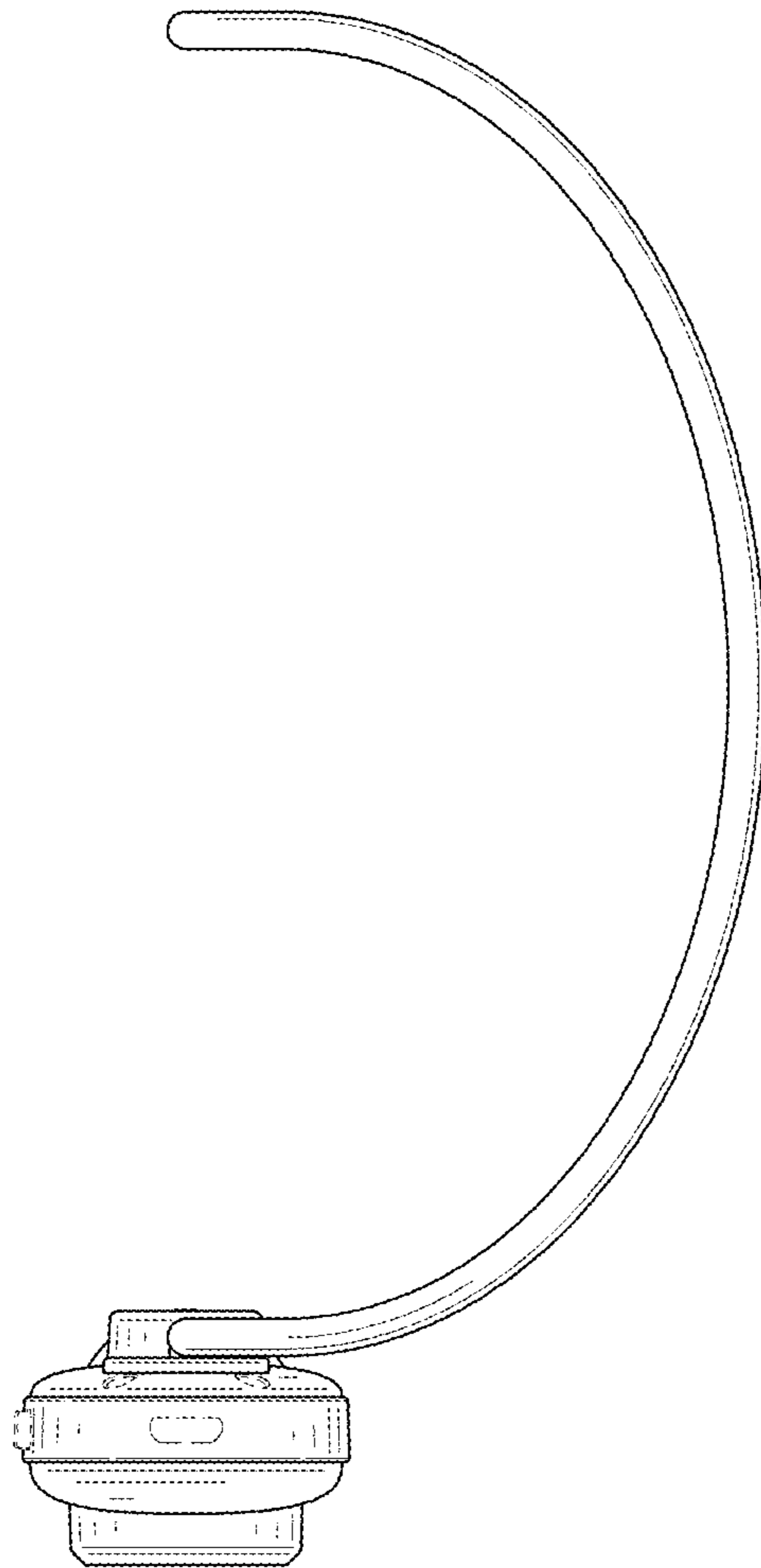


FIG. 6

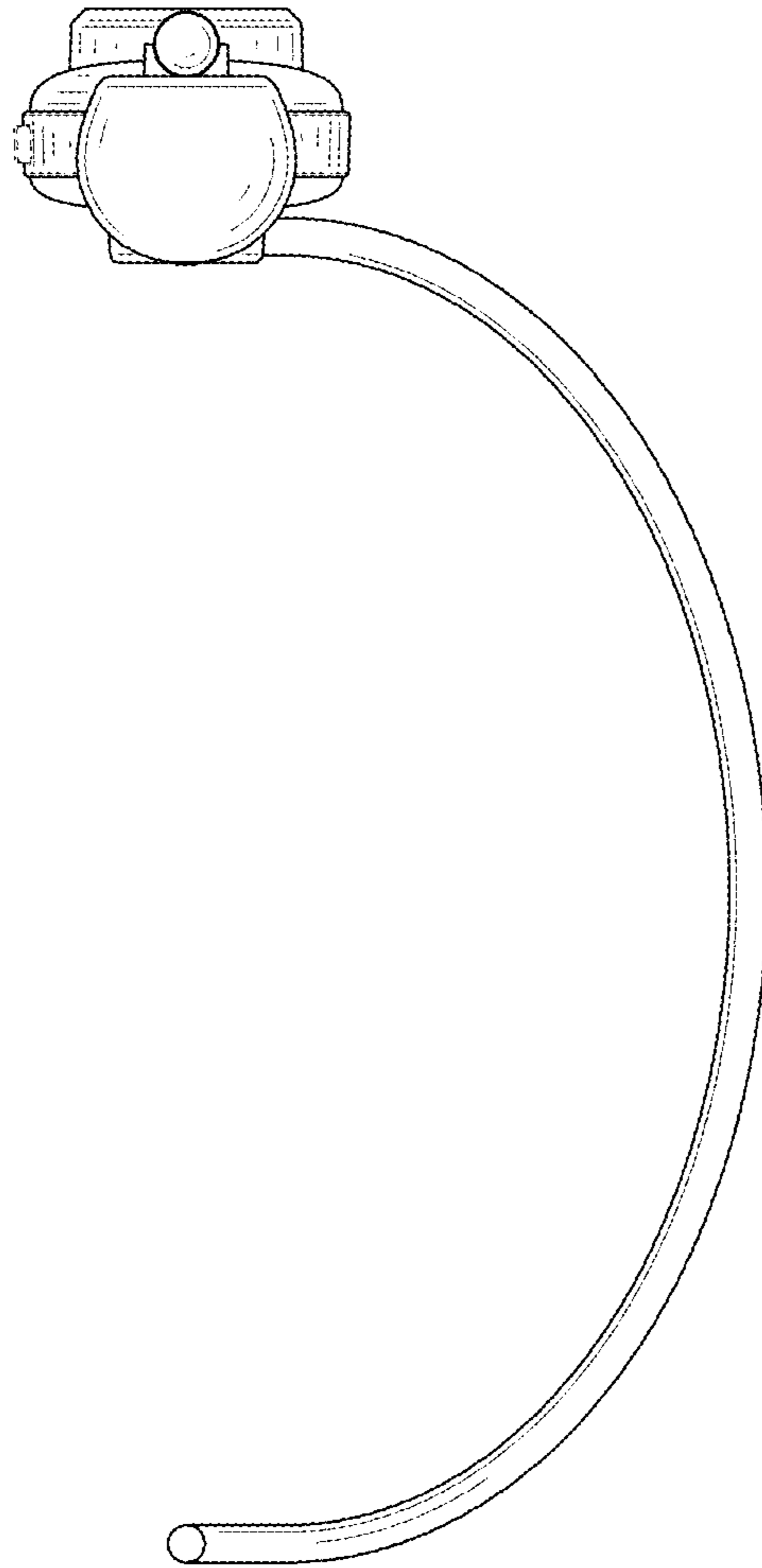


FIG. 7

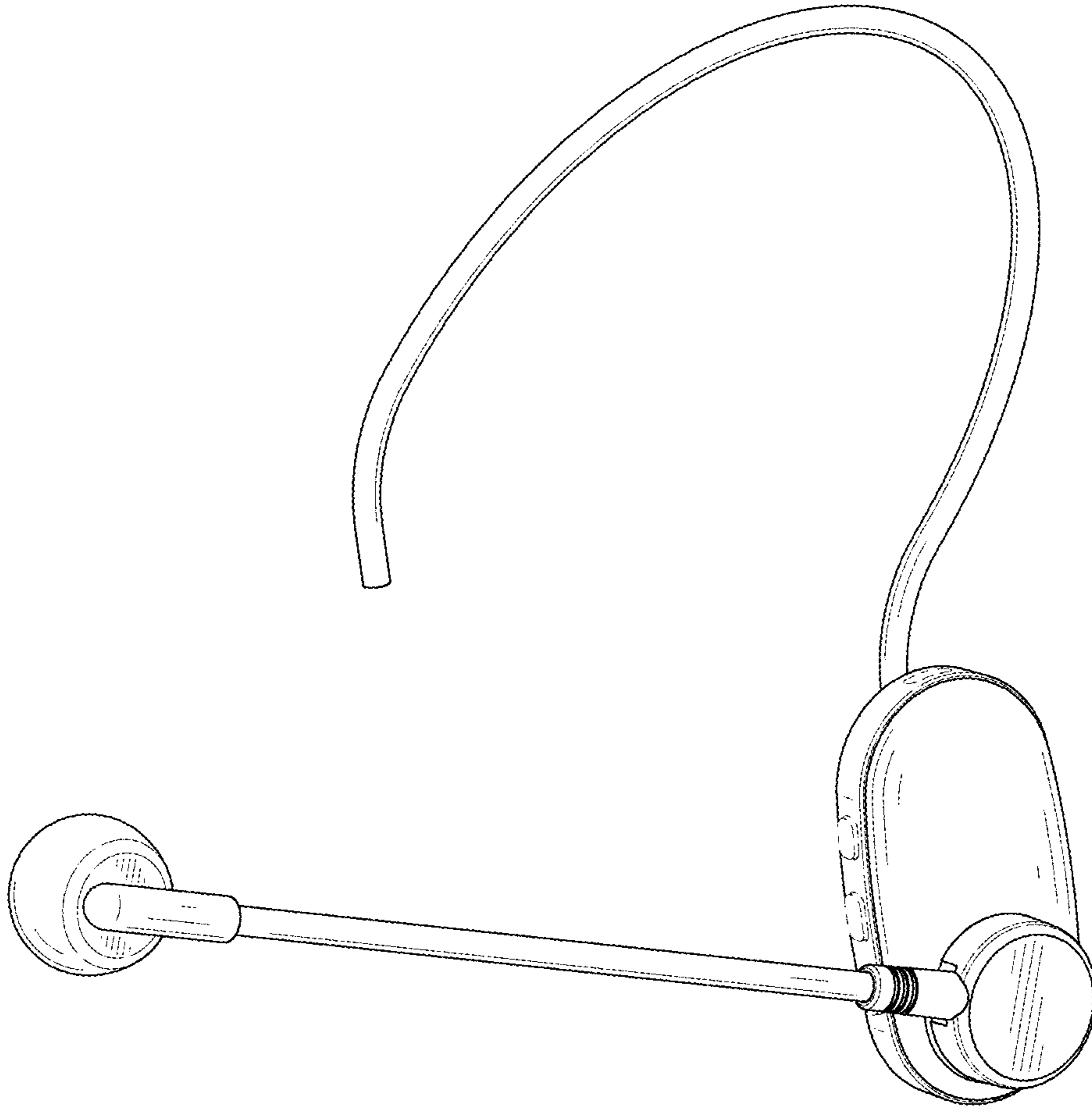


FIG. 8

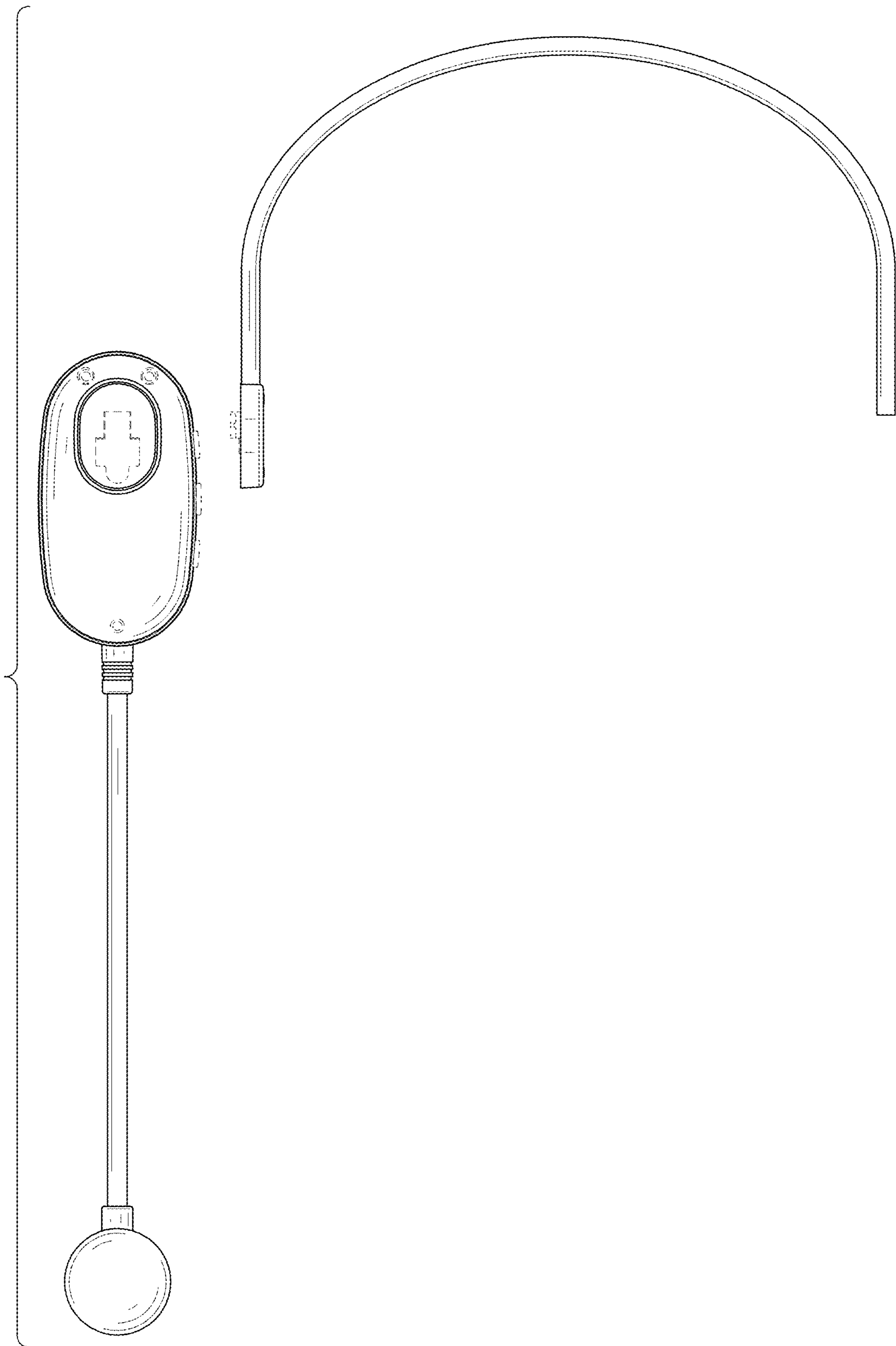


FIG. 9